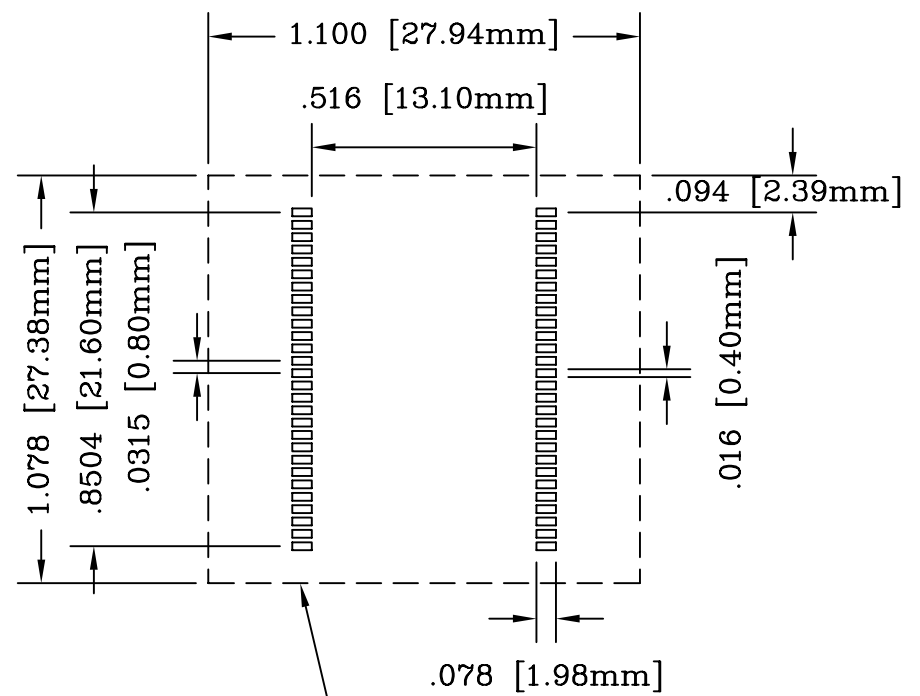
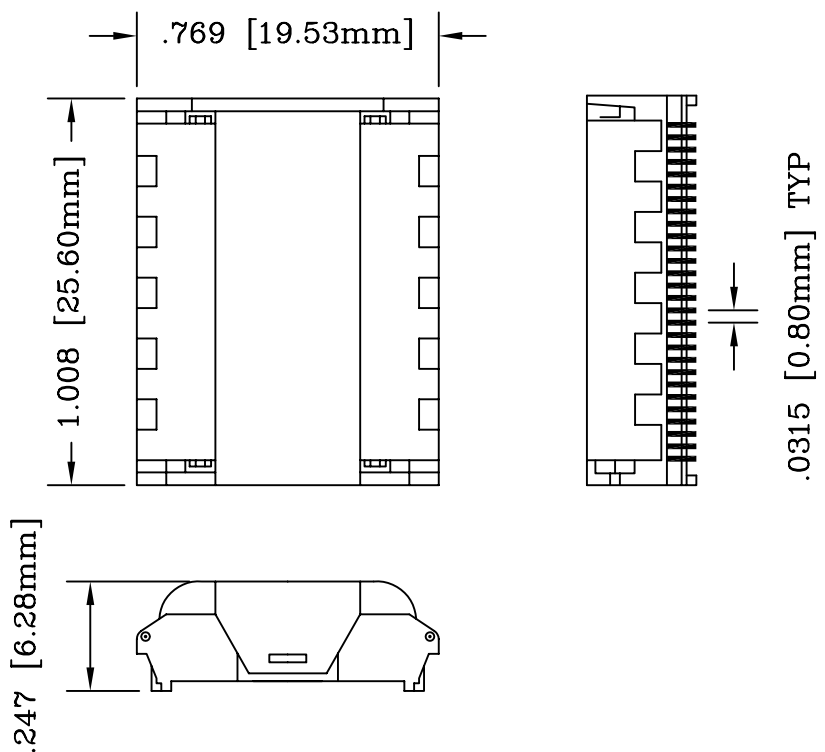


| | | | |
|-----|-------------|----------|------|
| REV | DESCRIPTION | DATE | BY |
| A | NEW DRAWING | 10/07/05 | H.N. |

SKT2449

NO ALIGNMENT PIN
 SOCKET LAND-PAD FOOTPRINT

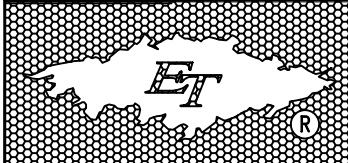


MINIMUM AREA CLEAR OF OTHER COMPONENTS

SPECIFICATIONS:

- FOR OEM, PROGRAMMING, PROTOTYPING AND TEST APPLICATIONS
- SURFACE MOUNT ZERO-INSERTION FORCE
- LAND-PAD FOOTPRINT COMMON FOR PACKAGE AND SOCKET
- PACKAGING: TRAY OR TAPE AND REEL
- BODY, LID AND LOCK MATERIAL: LCP
- TERMINAL MATERIAL: COPPER ALLOY, WITH PbSn PLATING
- MINIMUM INSERTION/WITHDRAWL CYCLES: 50
- TEMPERATURE RANGE: -55°C TO + 105°C
- CURRENT RATING: 0.5 AMP
- FLAMMABILITY: 94V-0
- POSITIVE LOCKING LID DESIGN

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.
 — VLSI and SMT ADAPTERS and ACCESSORIES —
 2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051
 TEL:(408)982-0660 FAX:(408)982-0664

| PACKAGE SPECIFICATIONS | |
|------------------------|-----------|
| PIN COUNT | ≡ 56 |
| LEAD PITCH | ≡ 0.80mm |
| PACKAGE WIDTH | ≡ 13.30mm |

| | | | |
|-----------------------|----------------------|-----------------------------|-------------------------|
| SHEET: 1 OF 1 | DATE: 10/07/05 | REVISION: A | ASSEMBLY DRAWING |
| CHECKED: Perry Munroe | DRAWN: Huy Nguyen | ITEM: S-SSO-SM-056-B | |
| Scale 2:1 | DO NOT SCALE DRAWING | DESCRIPTION: S-SSO-SM-056-B | |